



**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that:

My residence, post office address, and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled

Solder Ball Assembly for Bump Formation and Method for Its Manufacture

the specification of which

- (Check one)
- ☐ is attached hereto.
- ☒ was filed on December 10, 2003 as patent application Serial No. 10/731,436 and was amended on \_\_\_\_\_  
(if any).
- ☐ was filed on \_\_\_\_\_ as PCT International Application No. \_\_\_\_\_ and was amended under PCT Article 19 on \_\_\_\_\_  
(if any).

I have reviewed and understand the contents of the specification identified above, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information that is material to the examination of the patent application identified above in accordance with 37 CFR §1.56(a).

I claim foreign priority benefits pursuant to 35 U.S.C. §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application from which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

Japan                      2002-359405                      11 DEC 2002  
(Country)                      (Number)                      (Day/Month/Year Filed)

Yes X No   

\_\_\_\_\_  
(Country)                      (Number)                      (Day/Month/Year Filed)

Yes    No   

I claim the benefit pursuant to 35 U.S.C. §119(e) of any United States provisional application(s) listed below:

\_\_\_\_\_  
Application Serial No.                      Filing Date

\_\_\_\_\_  
Application Serial No.                      Filing Date

I claim the benefit pursuant to 35 U.S.C. §120 of any United States patent application(s) listed below and, insofar as the subject matter of each of the claims of this patent application is not disclosed in the prior United States patent application(s) in the manner provided by the first paragraph of 35 U.S.C. §112, I acknowledge the duty to disclose material information as defined in 37 CFR §1.56(a) effective between the filing date of the prior patent application(s) and the national or PCT international filing date of this patent application:

\_\_\_\_\_  
Application Serial No.                      Filing Date                      Status (Pat./Pend./Aban.)

\_\_\_\_\_  
Application Serial No.                      Filing Date                      Status (Pat./Pend./Aban.)

I appoint:

Michael Tobias, Reg. 32948

my attorney with full power of substitution and revocation to prosecute my application for Letters Patent identified above and to transact all business in the Patent and Trademark Office connected with that patent application.

I authorize my attorney to accept and follow instructions from S. Hirose and Associates regarding any matter related to the preparation, examination, grant, and maintenance of the application identified above, any continuation, continuation-in-part, or divisional based on the patent application identified above, and any patent issuing from that patent application, until I or my assigns withdraw this authorization in writing.

I direct that correspondence concerning this application be sent to Michael Tobias, #40, 1717 K Street N.W., Suite 613, Washington, D.C. 20036, telephone (301) 587-6541.

I declare that all statements made here based on my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the patent application identified above or any patent issuing from the patent application identified above.

Full name of sole or first inventor: Takeo KURAMOTO

Inventor's signature Takeo Kuramoto

Date 3/22/2004

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Citizenship: Japan

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Full name of second joint inventor, if any: Kaichi TSURUTA

Inventor's signature Kaichi Tsuruta

Date 3/22/2004

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Full name of third joint inventor, if any:

Inventor's signature \_\_\_\_\_

Date \_\_\_\_\_

Residence:

Citizenship: Japan

Post Office Address:

[ ] Additional inventors are being named on separately numbered sheets attached hereto.